

LNJ115W89RA

Surface Mounting Chip LED

TSS Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

- Green

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	60	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Lighting Color / Lens Color**

- Green / White Diffused
- Ultra Bright Soft Orange / White Diffused

- Ultra Bright Soft Orange

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.**■ Electro-Optical Characteristics** $T_a = 25^\circ\text{C}$

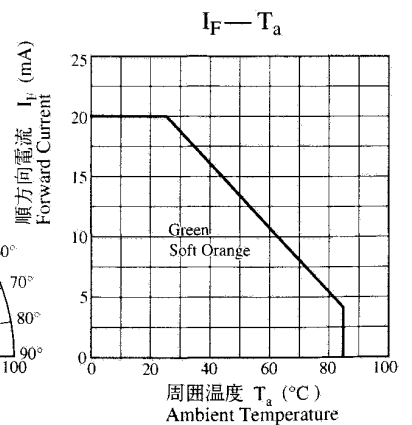
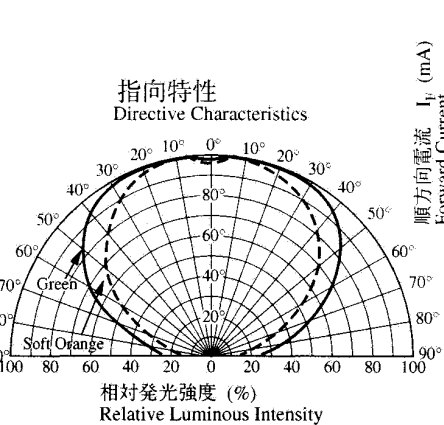
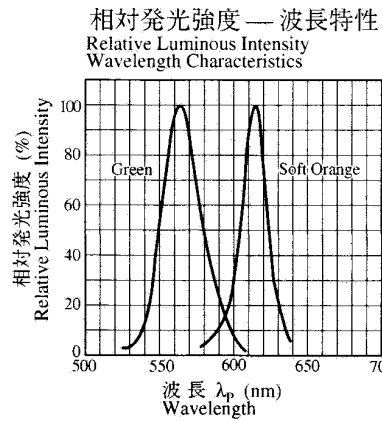
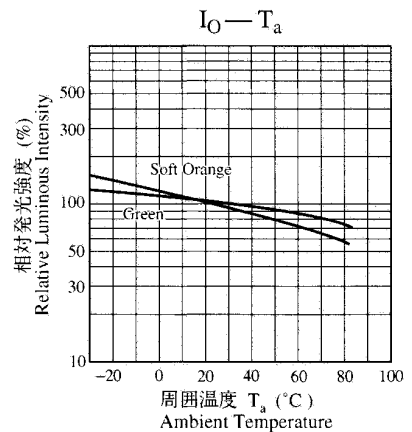
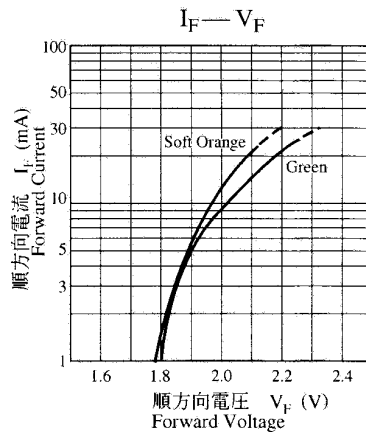
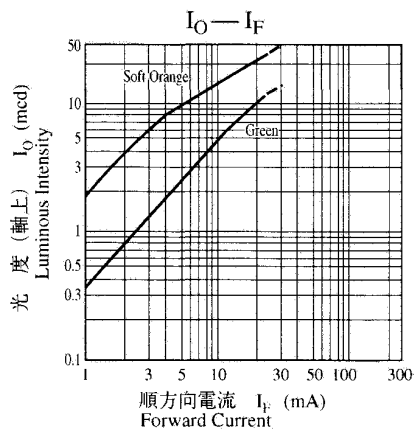
- Green

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		1.8	5.0		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		2.03	2.6	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		565		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		30		nm
Reverse current	I_R	$V_R = 4\text{ V}$			10	μA

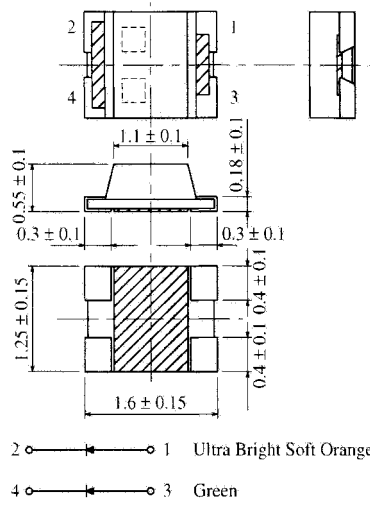
■ Electro-Optical Characteristics (Continued) $T_a = 25^\circ\text{C}$

• Ultra Bright Soft Orange

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		7	21		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.95	2.5	V
Peak emission wavelength	λ_p	$I_F = 10\text{ mA}$		615		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm
Reverse current	I_R	$V_R = 4\text{ V}$			100	μA



■ Package (Unit: mm)



• Pin name

1, 3: Anode

2, 4: Cathode

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